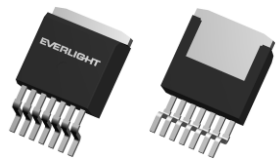


TO-263-7L 1700V N-Channel Enhancement SiC Power MOSFET EL-MAH01170XA

Preliminary



V_{DSS}	=	1700	V
I_D	=	5.2	A
$R_{DS(on)}$	=	1	Ω

Features

- Low on-resistance $R_{DS(on)}$
- Best thermal conductivity and behavior
- High speed switching
- High robustness of dv/dt
- Low capacitances and low gate charge



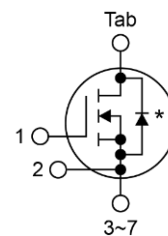
Benefits

- Improve System Efficiency
- Increase Power Density
- Reduce Heat Sink Requirement
- Reduction of System Cost

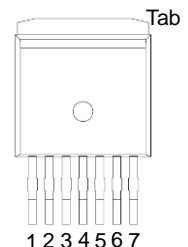
Applications

- Solar Inverters
- EV Battery Chargers
- High Voltage DC/DC Converters
- Switch Mode Power Supply

Schematic



Pin Configuration



- 1: Gate
- 2: Driver Source
- 3~7: Power Source
- Tab: Drain
- *: Body Diode

Key Performance Parameters

Symbol	V_{DSmin}	V_{GSS}	I_D	I_{DP}	$T_{J,max}$	P_D
Parameter	Drain-Source Voltage	Gate-Source Voltage (DC)	Continuous Drain Current	Pulse Drain Current	Junction temperature	Power Dissipation
Value	1700V	-4~20V	5.2A	-	175 °C	-

Maximum Ratings

Parameter	Symbol	Value	Unit	Test Conditions
Drain - Source Voltage	V_{DSmin}	1700	V	$V_{GS}= 0V, I_D= 250\mu A$
Gate - Source Voltage (DC) Max	V_{GS}	-4 / +20V	V	Recommended operating values
Continuous Drain Current	I_D^{*2}	5.2	A	
Pulse Drain Current	I_{DP}	-	A	
Power Dissipation	P_D^{*3}	-	W	
Operating Junction	T_J	175	°C	
Storage Temperature	T_{stg}	-55 to +175	°C	
Solder Temperature	T_L	260	°C	

*1 Please be advised not to use SiC-MOSFETs with V_{GS} below 12V as doing so may cause thermal runaway.

*2 Limited by maximum T_a and for Max. R_{thJC}

*3 $P_W \leq 10\mu s$, Duty cycle $\leq 1\%$

*4 Tested after applying V_{GS} for 100ms.

*5 Pulsed

Electrical Characteristics

Parameter	Symbol	Value			Unit	Test Conditions
		Min	Typ	Max		
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1700	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate Threshold Voltage	$V_{GS(th)}^{*4}$	2.0	-	4.0	V	$V_{DS}=10V, I_D=1.0mA$
Zero Gate Voltage Drain Current	I_{DSS}	-	0.4 12	6 -	μA	$V_{DS}=1700V, V_{GS}=0V, T_J=25^\circ C$ $V_{DS}=1700V, V_{GS}=0V, T_J=150^\circ C$
Gate-Source Leakage Current	I_{GSS+}	-	-	100	nA	$V_{GS}=20V, V_{DS}=0V$
Gate-Source Leakage Current	I_{GSS-}	-	-	-100	nA	$V_{GS}=-4V, V_{DS}=0V$
Drain-Source On-State Resistance	$R_{DS(on)}^{*5}$	-	780	1220	m Ω	$V_{GS}=18V, I_D=2.6A, T_J=25^\circ C$
		-	1500	-		$V_{GS}=18V, I_D=2.6A, T_J=125^\circ C$
Input Capacitance	C_{iss}	-	155	-	pF	$V_{GS}=0V$ $V_{DS}=1000V$ $f=1MHz$
Output Capacitance	C_{oss}	-	14	-		
Reverse Transfer Capacitance	C_{rss}	-	2	-		
Turn-On Switching Loss	E_{on}	-	-	-	μJ	-
Turn-Off Switching Loss	E_{off}	-	-	-	μJ	
Turn-On Delay Time	$t_{d(on)}$	-	-	-	ns	
Rise Time	t_r	-	-	-		
Turn-Off Delay Time	$t_{d(off)}$	-	-	-		
Fall Time	t_f	-	-	-		
Gate to Source Charge	Q_{gs}	-	1.7	-	nC	
Gate to Drain Charge	Q_{gd}	-	2.5	-		
Total Gate Charge	Q_g	-	8.9	-		

Body Diode Characteristics

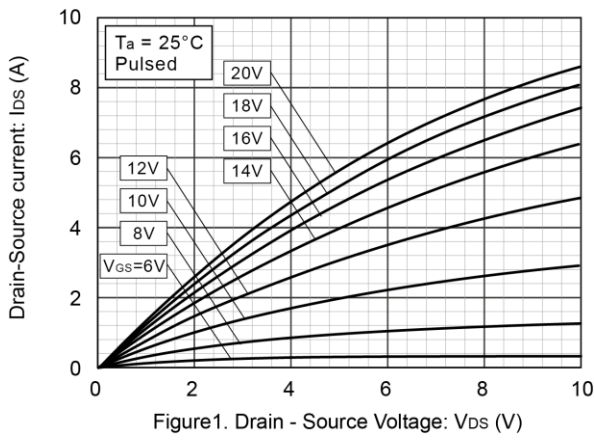
Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Diode Forward Voltage	V_{SD}	4.5	-	V	$V_{GS}= 0V, I_S= 2.6A$
Continuous Diode Forward Current	I_S	-	5.2	A	
Reverse Recover Time	t_{rr}	32	-	ns	
Peak Reverse Recovery Current	I_{rrm}	3.3	-	A	$I_S= 1.7A$ $V_R= 800V$ $di/dt= 500A/\mu s$
Reverse recovery charge	Q_{rr}	50	-	nC	

Thermal Characteristics (Measured conformable to JESD51-14.)

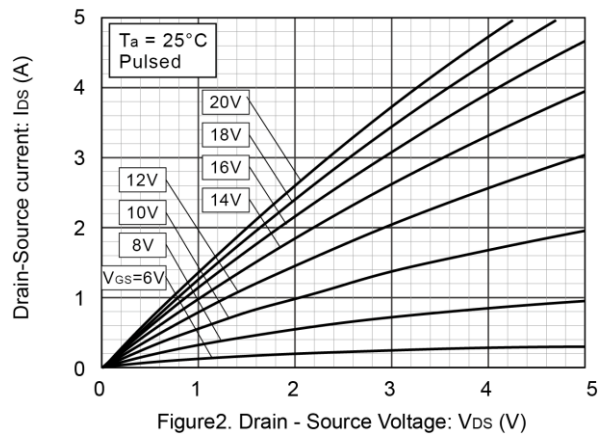
Parameter	Symbol	Value		Unit
		Typ	Max	
Thermal Resistance from Junction to Case	$R_{\theta JC}$	-	-	$^{\circ}C/W$

Typical Performance

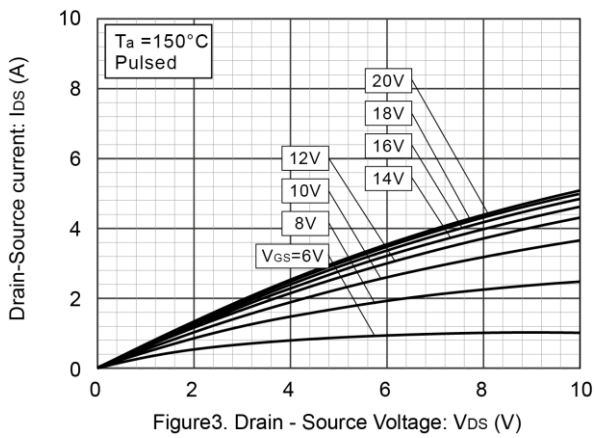
Typical Output Characteristics (I)



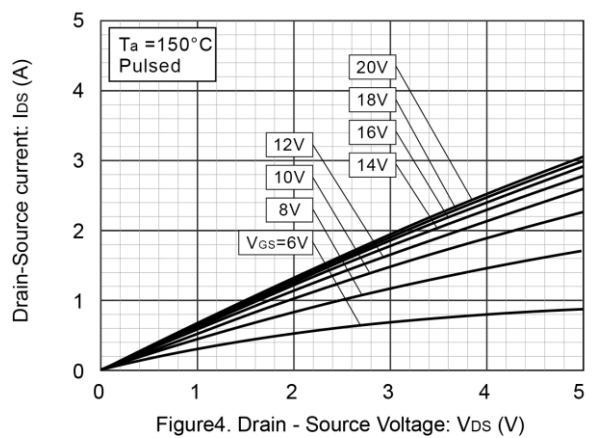
Typical Output Characteristics (II)



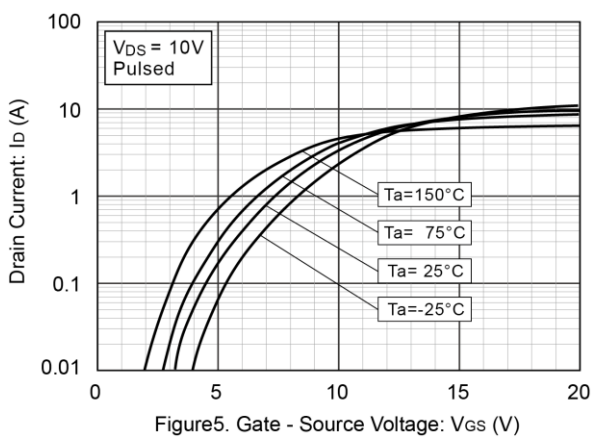
Typical Output Characteristics (III) $T_a = 150^\circ\text{C}$



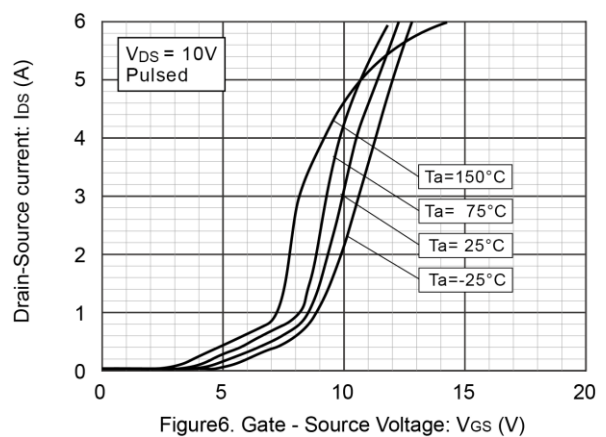
Typical Output Characteristics (IV) $T_a = 150^\circ\text{C}$



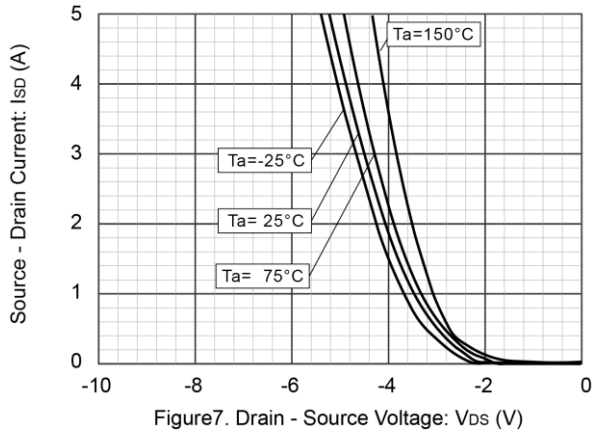
Typical Transfer Characteristics (I)



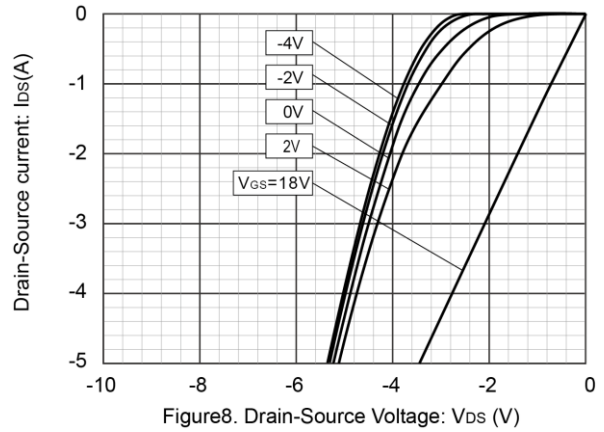
Typical Transfer Characteristics (II)



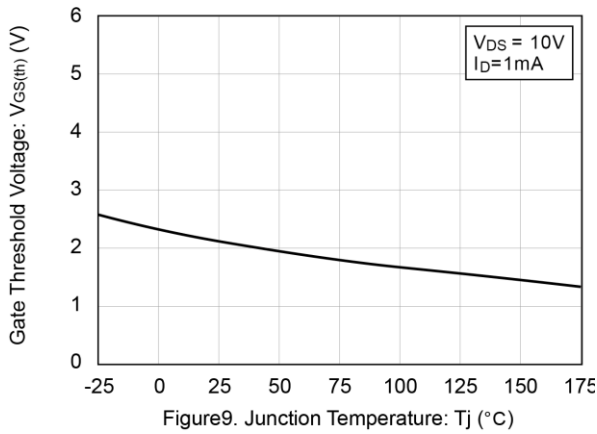
Drain – Source Voltage vs. Source - Drain current



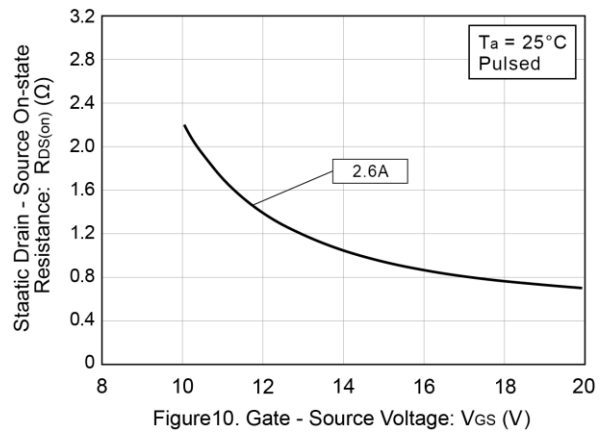
3rd Quadrant Characteristic $T_a = 25^\circ\text{C}$



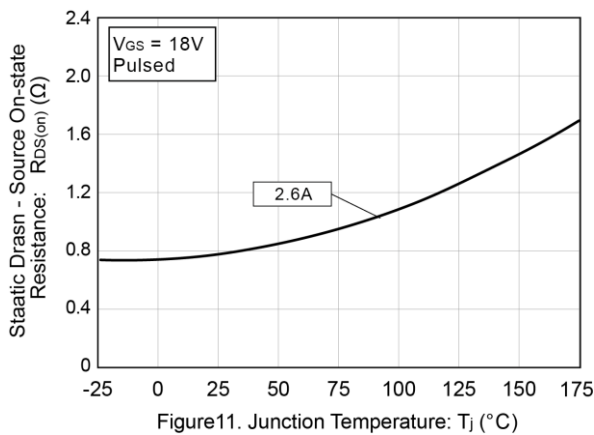
Gate Threshold Voltage vs. Junction Temperature



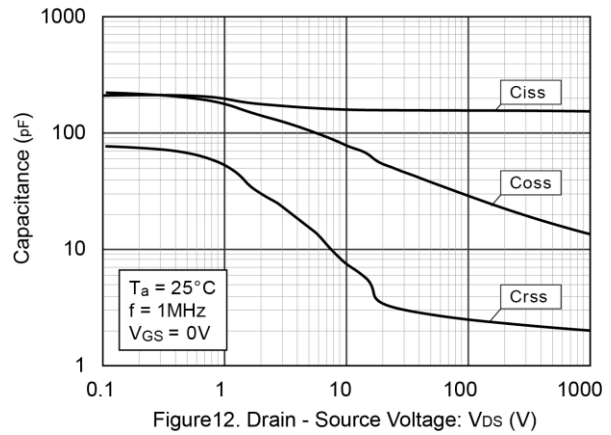
Static Drain - Source On - State Resistance vs. Gate - Source Voltage



Static Drain - Source On - State Resistance vs. Junction Temperature



Typical Capacitance vs. Drain – Source Voltage



Typical Gate Charge

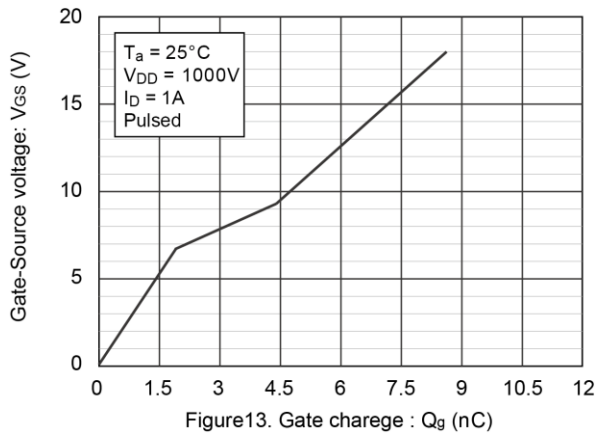
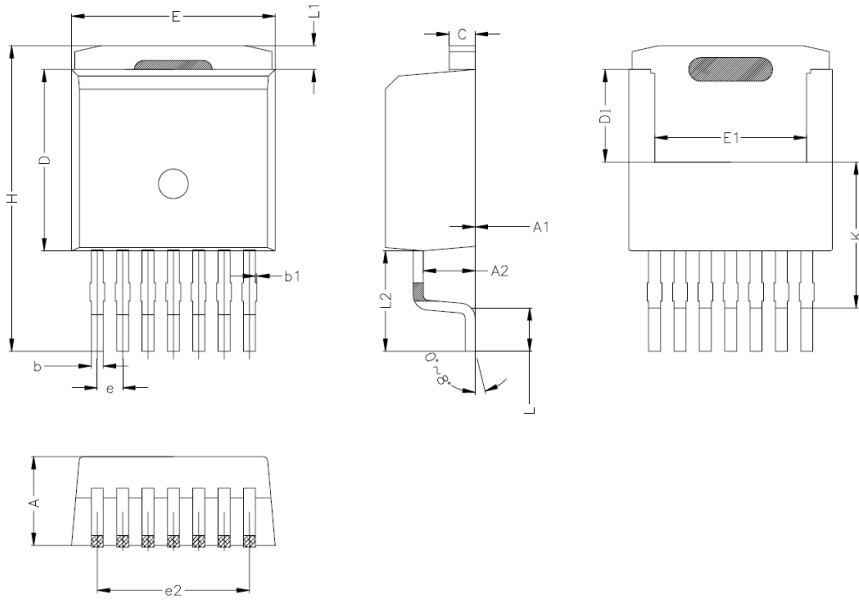


Figure13. Gate charge : Q_g (nC)

Package Outlines

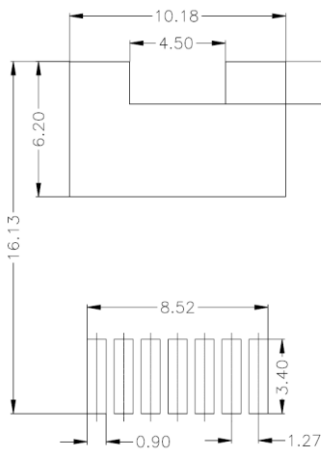


DIM	MILLIMETERS		
	MIN	TYP	MAX
A	4.30	4.50	4.70
A1	0.00	0.15	0.30
A2	2.50	2.60	2.70
b	0.50	0.60	0.70
b1			0.25
C	1.20	1.30	1.40
D	9.00	9.20	9.40
D1	4.45	4.70	4.95
E	10.00	10.20	10.40
E1	7.35	7.60	7.85
e	1.27 BSC		
e2	7.62 BSC		
H	15.25	15.50	15.75
L	1.95	2.20	2.45
L1	0.95	1.20	1.45
L2	4.85	5.10	5.35
K	7.20	7.40	7.60

Unit : mm

Drawing and Dimensions

Recommended pad layout for surface mount leadform



Unit : mm

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